

Press Release

New 3D X-ray system from Viscom wins productronica innovation award

Hanover, November 2017 – productronica 2017, hall 2A, stand no. 177
Viscom AG has received the productronica innovation award in the category Inspection & Quality at this year's productronica trade fair, November 14-17, in Munich, Germany. The winner is the newest system for automatic 3D X-ray inspection, the X7056-II.

The X7056-II is the next generation of the highly regarded X7056RS model. The new board handling solution xFastFlow makes the X7056-II ideal for use in production lines that require high throughput despite extensive inspection of hidden solder joints. Up to three PCBs can be processed simultaneously in the system. Through use of xFastFlow, it is now possible to achieve handling times (component infeed and outfeed) of even less than four seconds. Due to the time saved, 3D inspections, which used to be done selectively, can be expanded to cover far more than just individual components.

For an optimum configuration of the X7056-II, high-performance flat panel detectors (FPD) are available in different sizes, and e.g., with an xy-table for planar CT. Inspection depth and throughput are flexibly adaptable to meet individual requirements. 2D, 2.5D and 3D inspection can be combined to run in succession for ultimate coverage. Images are acquired from as many different angles as necessary in a single pass and three-dimensional digital reconstructions of inspected objects become highly accurate.

With Viscom's own development of state-of-the-art planar CT software algorithms, the system offers new 3D AXI image reconstruction procedures that reduce interfering structures more effectively than ever before. Even from double-sided printed circuit boards with a very complex overlap of components on both sides easy-to-analyze layers can be mathematically extracted. The X7056-II automatically resolves any covered areas to clearly reveal important defect features and allow exact evaluations.

As with the predecessor system, an optional combination with automatic optical inspection (3D AOI) in one machine housing is a fixed component of the development. The X7056-II can offer the high optical inspection depth of the newest Viscom AOI solutions, and this with comparable throughput. Investment spending is reduced as AOI and AXI are optimized effectively within just one system. By taking advantage of the third dimension, users have the benefit of an unshadowed view of all components and solder joints.

Furthermore, customers can now choose between Viscom's state-of-the-art vVision and EasyPro (SI) inspection software. vVision provides intuitive operation as well as quick generation of multiple inspection programs. Effective networking and up-to-date statistical process control are also important features of the X7056-II.



The new Viscom 3D X-ray inspection system X7056-II – winner of the productronica innovation award 2017

About Viscom

Viscom AG develops, manufactures and sells high-quality inspection systems. The portfolio encompasses the complete bandwidth of optical and X-ray inspections. In the area of assembly inspection for electronics manufacturing, the company is among the leading suppliers worldwide. Viscom systems can be configured specifically to the customer and can be interlinked. The company headquarters and manufacturing location is in Hanover, Germany. With a wide network of branches, applications centers, service support points and representatives, Viscom is represented internationally. Founded in 1984, Viscom has been listed on the Frankfurt Stock Exchange (ISIN: DE0007846867) since 2006. For additional information, visit www.viscom.com